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(54) **LED MODULE**

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CPC **H01L 25/0753** (2013.01); **H01L 33/486** (2013.01); **H01L 33/62** (2013.01); **H01L 2224/32245** (2013.01); **H01L 2224/48247** (2013.01); **H01L 2224/48465** (2013.01); **H01L 2224/73265** (2013.01)

(58) **Field of Classification Search**

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See application file for complete search history.

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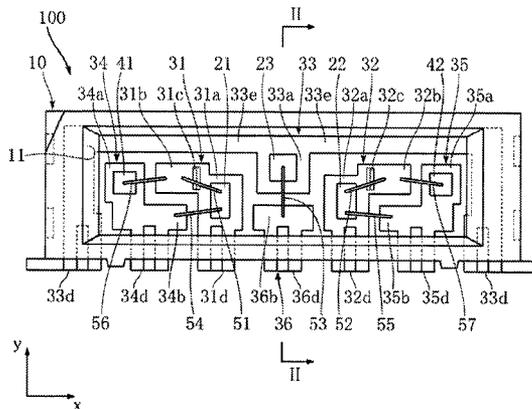
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(57) **ABSTRACT**

An LED module 100 includes LED chips 21, 22 spaced apart from each other, and an LED chip 23 offset from a straight line connecting the LED chips 21 and 22 and located between the LED chips 21, 22 in the direction in which the LED chips 21, 22 are spaced. The module further includes a lead 31 with a bonding portion 31a and a mounting terminal surface 31d, a lead 32 with a bonding portion 32a and a mounting terminal surface 32d, and a lead 33 with a bonding portion 33a and a mounting terminal surface 33d. The mounting terminal surfaces 31d, 32d, 33d are flush with each other. Light from the LED chips 21, 22, 23 is emitted in the direction in which the mounting terminal surfaces 31d, 32d and 33d extend. Thus, light of different colors properly mixed can be emitted from a compact LED module.

10 Claims, 6 Drawing Sheets



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FIG. 1

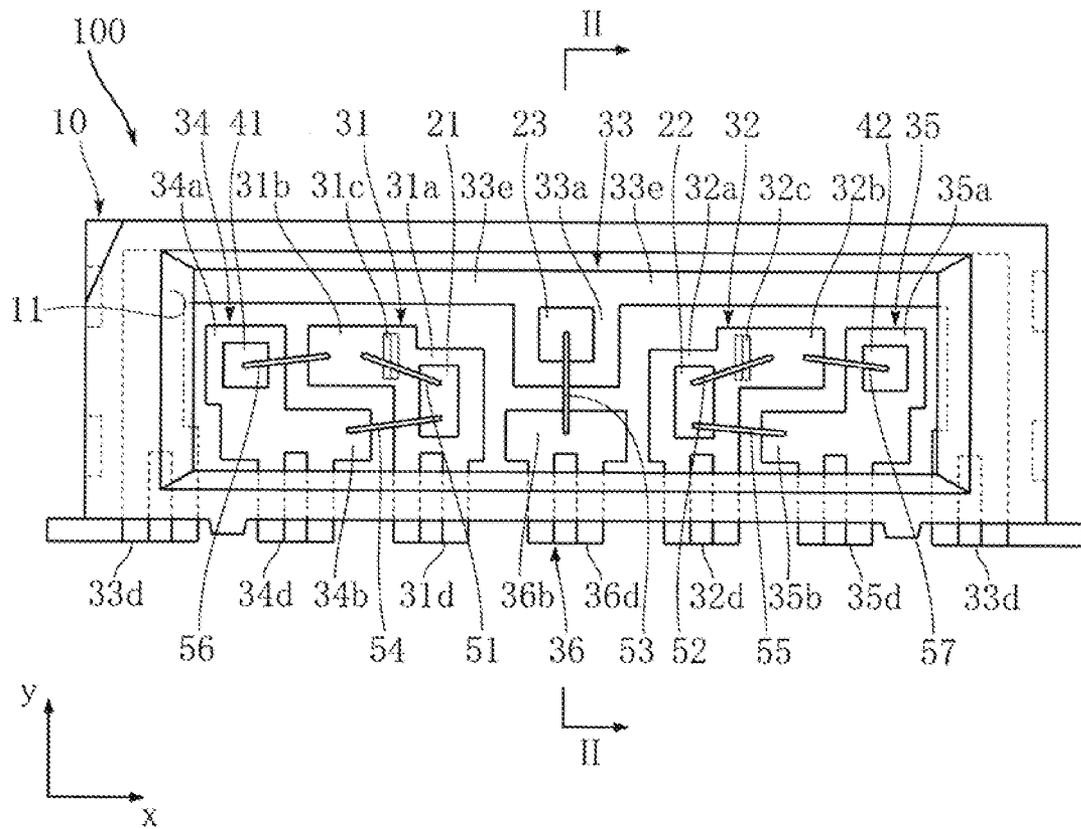


FIG. 2

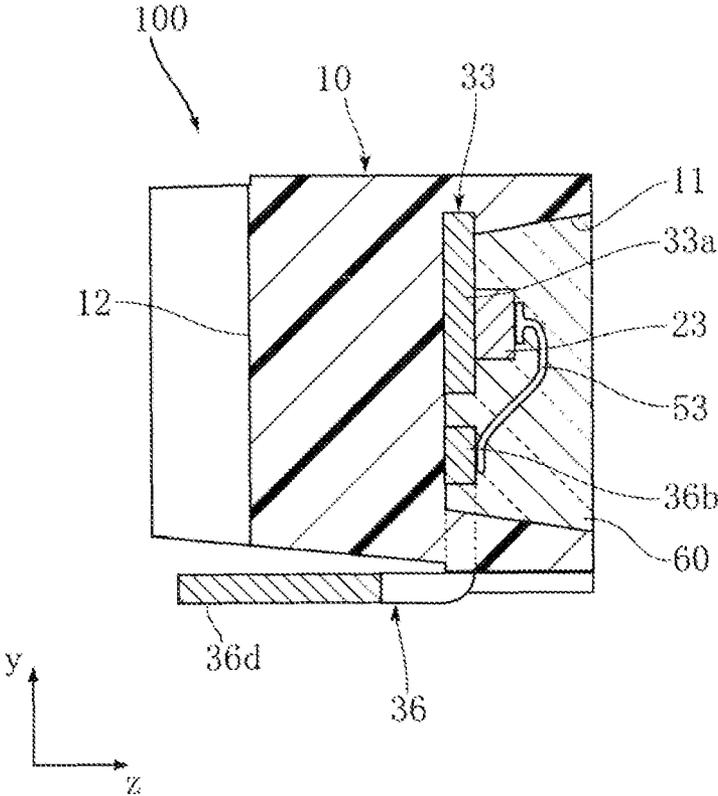


FIG.3

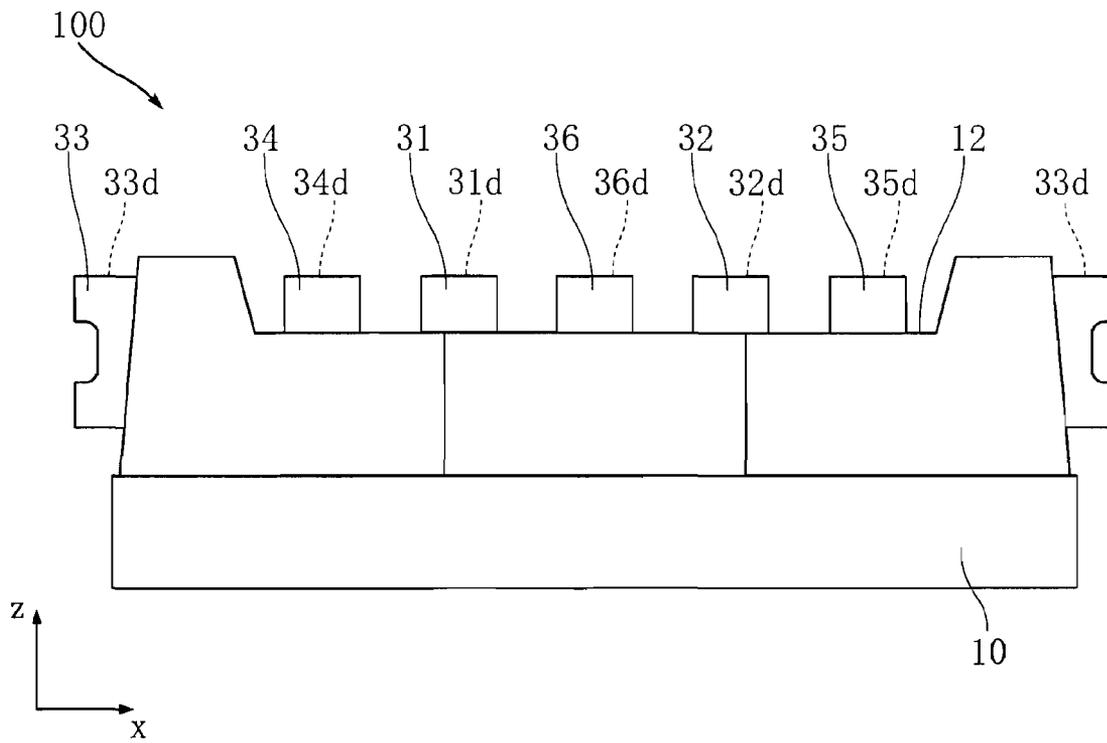


FIG. 4

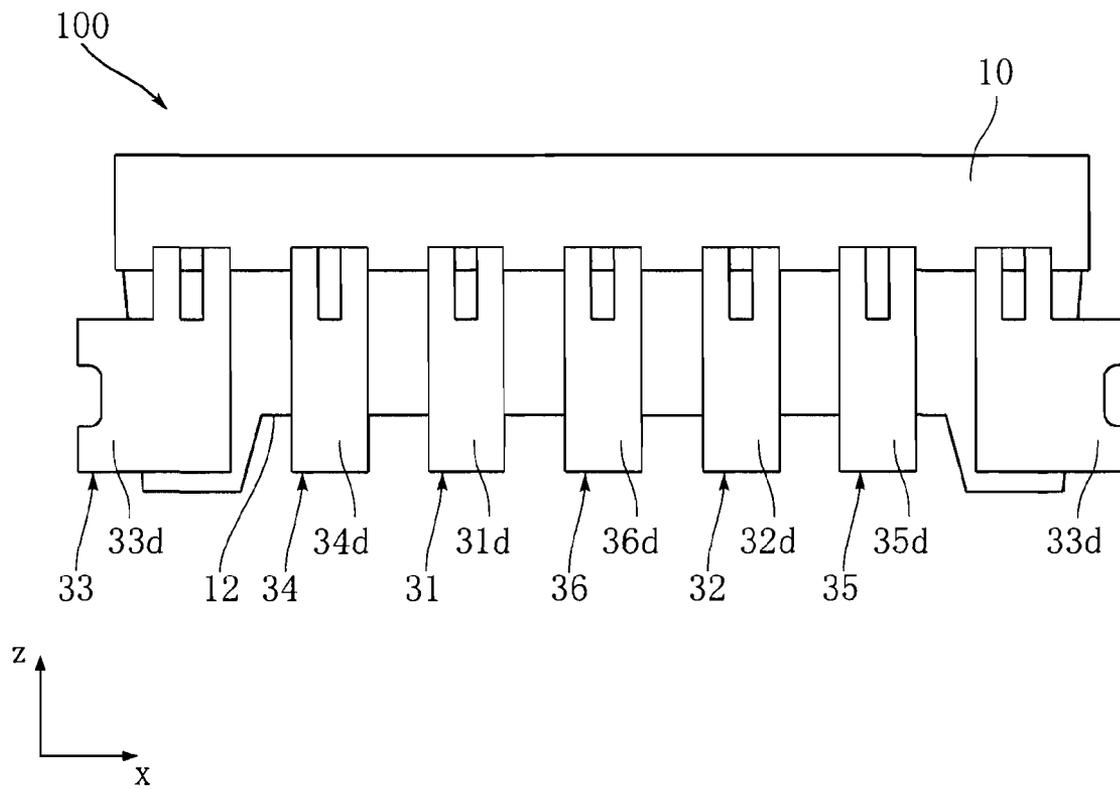


FIG. 5

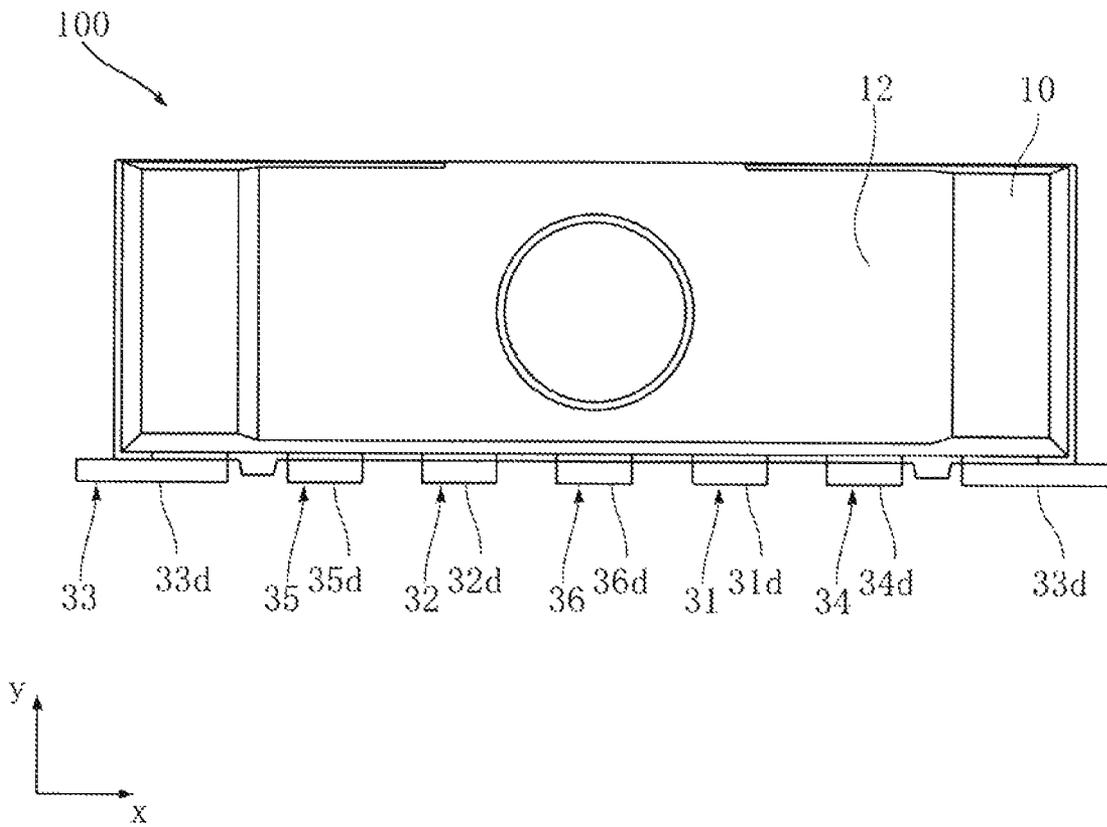


FIG. 6

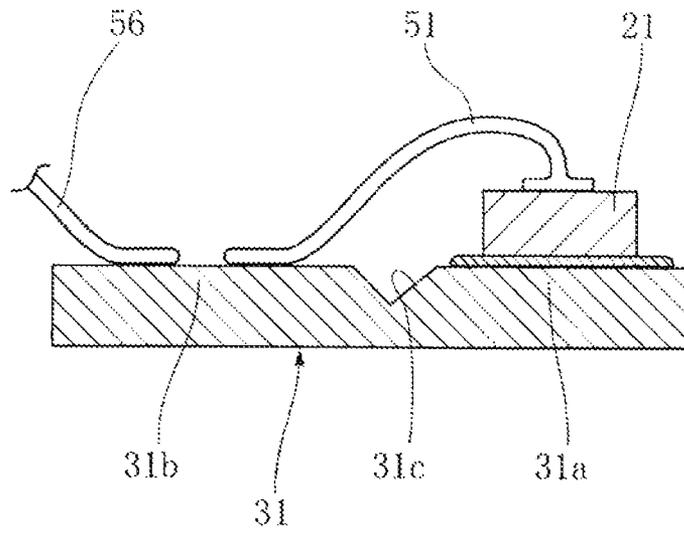
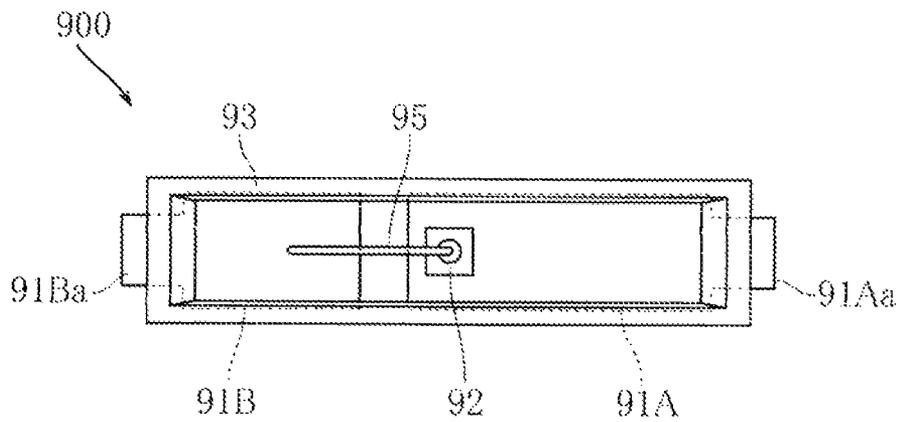


FIG. 7
PRIOR ART



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LED MODULE

TECHNICAL FIELD

The present invention relates to an LED module of a so-called side-view type.

BACKGROUND ART

FIG. 7 shows an example of a conventional LED module. The LED module **900** illustrated in the figure includes leads **91A** and **91B**, an LED chip **92**, and a case **93** and is configured as a so-called side-view type. The leads **91A** and **91B** each comprises a plate made of e.g. art alloy of Cu or Ni plated with Ag. The LED chip **92** is mounted on the lead **91A**. The LED chip **92** is configured to emit e.g. blue light. The LED chip **92** and the lead **91B** are connected to each other with a wire **95**. The case **93** is made of e.g. white resin and surrounds the four sides of the LED chip **92**. Portions of the leads **91A** and **91B** that are exposed from the case **93** serve as mounting terminals **91Aa** and **91Ba**. The space surrounded by the case **93** is filled with light-transmitting resin, not shown. The light-transmitting resin is made of e.g. a transparent resin mixed with a fluorescent substance. The fluorescent substance emits e.g. yellow light when excited by the light emitted from the LED chip **92**. The blue light from the LED chip **92** and the yellow light from the fluorescent substance mix with each other, so that white light is emitted from the LED module **900**.

One of the means for increasing the application of the LED module **900** is to configure the LED module to emit light of a plurality of colors, instead of a single color. For this purpose, it is necessary to provide a plurality of LED chips **92** that emit light of different wavelengths from each other. However, in the LED module **900** of a side-view type, the height (the dimension in the vertical direction in the figure) is often limited to a certain value. Thus, it is desirable to arrange the LED chips **92** as close to each other as possible. Further, when the LED chips **92** are too far away from each other, light of different colors cannot sufficiently mix with each other when all the LED chips **92** are turned on.

Patent Document: JP-A-2006-253551

SUMMARY OF THE INVENTION

Problems to be Solved by the Invention

The present invention has been conceived in view of the foregoing situation. It is therefore an object of the present invention to provide an LED module that is configured to properly mix light of a plurality of colors for emission and that can be made compact.

Means for Solving the Problems

An LED module provided according to a first aspect of the present invention comprises: at least one LED chip; at least one lead including a bonding portion on which the LED chip is mounted and a mounting terminal surface for surface mounting; and a case covering a part of the lead. Light from the LED chip is emitted in the direction in which the mounting terminal surface extends. In an embodiment, the LED module includes a first and a second LED chips spaced apart from each other, and a third LED chip arranged at a position that is offset from a straight line connecting the first and the second LED chips, where the above-mentioned position is

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spacing direction in which the first and the second LED chips are spaced apart from each other.

In another embodiment according to a first aspect of the present invention, there is provided an LED module comprises: a first and a second LED chips spaced apart from each other; a third LED chip arranged at a position that is offset from a straight line connecting the first and the second LED chips, the above-mentioned position being between the first LED chip and the second LED chip in a spacing direction in which the first and the second LED chips are spaced apart from each other; a first lead including a first bonding portion on which the first LED chip is mounted and a first mounting terminal surface for surface-mounting; a second lead including a second bonding portion on which the second LED chip is mounted and a second mounting terminal surface for surface-mounting; and a third lead including a third bonding portion on which the third LED chip is mounted and a third mounting terminal surface for surface-mounting. The first through the third mounting terminal surfaces are flush with each other, and light from each of the first through the third LED chips is emitted in a direction in which the first through the third mounting terminal surfaces extend.

According to a second aspect of the present invention, in the LED module of the first aspect, one of the first and the second LED chips emits blue light, the other one of the first and the second LED chips emits green light, and the third LED chip emits red light.

According to a third aspect of the present invention, the LED module of the second aspect further comprises a third wire including an end bonded to the third LED chip and extending across the straight line connecting the first and the second LED chips.

According to a fourth aspect of the present invention, the LED module of the second or third aspect further comprises a first wire including an end bonded to the first LED chip and extending away from the third LED chip in the spacing direction.

According to a fifth aspect of the present invention, in the LED module of any one of the first through fourth aspects, the third lead comprises a detour portion extending in the spacing direction and passing at least one of the first and the second LED chips, where the detour portion is provided between the third bonding portion and the third mounting terminal surface.

According to a sixth aspect of the present invention, in the LED module of any one of the first through fifth aspects, the first lead comprises a first wire bonding portion to which another end of the first wire is bonded and a groove positioned between the first bonding portion and the first wire bonding portion.

According to a seventh aspect of the present invention, the LED module of any one of the first through sixth aspects further comprises a Zener diode arranged opposite to the third LED chip with respect to the first LED chip in the spacing direction, where the Zener diode is connected in series to the first LED chip.

According to an eighth aspect of the present invention, the LED module of any one of the first through seventh aspects further comprises: a first additional wire including an end bonded to the first LED chip; a fourth lead including a fourth wire bonding portion to which another end of the first additional wire is bonded and also including a fourth mounting terminal surface for surface mounting; a second additional wire including an end bonded to the second LED chip; a fifth lead including a fifth wire bonding portion to which another end of the second additional wire is bonded and also including a fifth mounting terminal surface for surface mounting; a third

wire including an end bonded to the third LED chip; and a sixth lead including a sixth wire bonding portion to which another end of the third wire is bonded and also including a sixth mounting terminal surface for surface mounting. The first through sixth mounting terminal surfaces are flush with each other.

According to a ninth aspect of the present invention, in the LED module of the eighth aspect, the case is provided with a recess, and the first through sixth leads include surfaces opposite to the first through the sixth mounting terminal surfaces, respectively. The recess of the case is configured to expose at least a part of each of the opposite surfaces of of the first through the sixth leads, as viewed from a side opposite to a direction in which the first through the sixth mounting terminal surfaces face.

According to a tenth aspect of the present invention, in the LED module of any one of the first through ninth aspects, the case is provided with a reflector surrounding the first through third LED chips.

According to an eleventh aspect of the present invention, in the LED module of the tenth aspect, the reflector surrounds a region filled with light-transmitting resin covering the first through third LED chips.

Other features and advantages of the present invention will become more apparent from detailed description given below with reference to the accompanying drawings.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a front view of an example of LED module according to the present invention;

FIG. 2 is a sectional view taken along lines II-II in FIG. 1;

FIG. 3 is a plan view of the example of the LED module according to the present invention;

FIG. 4 is a bottom view of the example of the LED module according to the present invention;

FIG. 5 is a rear view of the example of the LED module according to the present invention;

FIG. 6 is a schematic sectional view showing a groove of the LED module according to the present invention; and

FIG. 7 is a front view of an example of conventional LED module.

MODE FOR CARRYING OUT THE INVENTION

Preferred embodiments of the present invention are described below with reference to the accompanying drawings.

FIGS. 1-6 show an example of LED module according to the present invention. The LED module 100 of this embodiment includes a case 10, LED chips 21, 22 and 23, leads 31, 32, 33, 34, 35 and 36, Zener diodes 41 and 42, wires 51, 52, 53, 54, 55, 56 and 57, and light-transmitting resin 60. The LED module 100 is configured as a side-view type that emits light mainly in the direction z, and its dimensions are e.g. about 6.9 mm in the direction x, about 2.15 mm in the direction y and about 2.2 mm in the direction z. The LED module 100 is made by insert molding. Note that illustration of the light-transmitting resin 60 is omitted in FIG. 1.

The case 100 provides the base of the LED module 100 and is made of e.g. white resin. The case has a reflector 11 and a recess 12. The reflector 11 surrounds the LED chips 21, 22 and 23. Light emitted from the LED chips 21, 22 and 23 in the direction x and the direction y is reflected by the reflector to travel in the direction z. The region surrounded by the reflector 11 has dimensions of about 5.4 mm in the direction x and about 1.6 mm in the direction y. As shown in FIGS. 3-5, the

recess 12 is provided on a side of the case 10 opposite to the light-emitting side in the direction y. The recess 12 has a uniform cross section as viewed in the direction z. The cross sectional shape is generally a flat trapezoid, elongated in the direction x.

The LED chips 21, 22 and 23 are the light source of the LED module 100. The LED chip 21 corresponds to the first LED chip defined in the present invention. The LED chip 21 has a laminated structure made up of an n-type semiconductor layer mainly composed of e.g. GaN, an active layer and a p-type semiconductor layer and emits blue light. The LED chip 22 corresponds to the second LED chip defined in the present invention. The LED chip 22 has a laminated structure made up of an n-type semiconductor layer mainly composed of e.g. GaN, an active layer and a p-type semiconductor layer and emits green light. The LED chip 23 corresponds to the third LED chip defined in the present invention. The LED chip 23 has a laminated structure made up of an n-type semiconductor layer mainly composed of e.g. Al, GaAs or GaAsP, an active layer and a p-type semiconductor layer and emits red light. In this embodiment, the LED chips 21 and 22 are configured as a two-wire type, whereas the LED chip 23 is configured as a single-wire type.

The Zener diodes 41 and 42 prevent application of excessive reverse voltage to the LED chips 21 and 22, respectively, and allow current to flow in a reverse direction only when an excessive reverse voltage above a certain value is applied.

The leads 31, 32, 33, 34, 35 and 36 serve to support the LED chips 21, 22, 23 and supply electric power. Each of the leads may comprise a plate made of e.g. an alloy of Cu or Ni plated with Ag. Each lead 31, 32, 33, 34, 35, 36 is partially covered by the case 10, and the remaining portion is exposed out of the case 10.

The lead 31 corresponds to the first lead defined in the present invention and includes a bonding portion 31a, a wire bonding portion 31b, a groove 31c and a mounting terminal surface 31d. As shown in FIG. 1, the bonding portion 31a, the wire bonding portion 31b and the groove 31c are arranged in the region surrounded by the reflector 11 at a position shifted slightly to the left from the center in the direction x.

To the bonding portion 31a is die-bonded the LED chip 21. The wire bonding portion 31b is on the left side of the bonding portion 31a in the direction x. To this wire bonding portion are bonded an end of the wire 51 and an end of the wire 56. The other end of the wire 51 is bonded to the LED chip 21. The other end of the wire 56 is bonded to the Zener diode 41. The groove 31c is positioned between the bonding portion 31a and the wire bonding portion 31b. The groove 31c extends in the direction y as shown in FIG. 1 and has e.g. a triangular cross-sectional shape as shown in FIG. 6.

Of the lead 31, the portion projecting from the case 10 downward in the direction y in FIG. 1 is bent to extend in the direction z, as shown in FIGS. 1, 2, 4 and 5. Of this portion, the surface that faces downward in the direction y in FIG. 1 is the mounting terminal surface 31d. The bent portion extends to overlap the recess 12 of the case 10 in the direction z.

The lead 32 corresponds to the second lead defined in the present invention and includes a bonding portion 32a, a wire bonding portion 32b, a groove 32c and amounting terminal surface 32d. As shown in FIG. 1, the shape of the lead 32 is symmetrical with the lead 31 with respect to an axis extending in the direction y. The bonding portion 32a, the wire bonding portion 32b and the groove 32c are arranged in the region

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surrounded by the reflector **11** at a position shifted slightly to the right from the center in the direction *x*.

To the bonding portion **32a** is die-bonded the LED chip **22**. The wire bonding portion **32b** is on the right side of the bonding portion **32a** in the direction *x*. To this wire bonding portion are bonded an end of the wire **52** and an end of the wire **57**. The other end of the wire **52** is bonded to the LED chip **22**. The other end of the wire **57** is bonded to the Zener diode **42**. The groove **32c** is positioned between the bonding portion **32a** and the wire bonding portion **32b**. The shape and size of the groove **32c** are the same as those of the groove **31c**.

Of the lead **32**, the portion projecting from the case **10** downward in the direction *y* in FIG. **1** is bent to extend in the direction **2**, as shown in FIGS. **1**, **2**, **4** and **5**. Of this portion, the surface that faces downward in the direction *y* in FIG. **1** is the mounting terminal surface **32d**. The bent portion extends to overlap the recess **12** of the case **10** in the direction *z*.

The lead **33** corresponds to the third lead defined in the present invention and includes a bonding portion **33a**, a detour portion **33e** and a mounting terminal surface **33d**. As shown in FIG. **1**, the bonding portion **33a** is arranged at the center in the direction *x* in the region surrounded by the reflector **11**. Also, the bonding portion **33a** is at an upper position relative to the bonding portions **31a** and **32a** in the direction *y* in FIG. **1**. To the bonding portion **33a** is bonded the LED chip **23** via a conductive material.

The detour portion **33e** includes a portion extending in the direction *x* from the bonding portion **33a** to both sides, and portions extending in the direction *y*. The two ends of the detour portion **33e**, which are spaced apart from each other in the direction *x*, are on the outer side of the corresponding two ends of the reflector **11** that are spaced apart in the direction *x*. Of the lead **33**, two portions extending from the detour portion **33e** project downward from the case **10** in the direction *y* in the figure. These portions are bent to extend in the direction *z*, as shown in FIGS. **1**, **2**, **4** and **5**. Of these portions, the surfaces that face downward in the direction *y* in FIG. **1** are the mounting terminal surfaces **33d**. Thus, the LED module of this embodiment has two mounting terminal surfaces **33d** that are spaced apart from each other in the direction *x*. As shown in FIG. **3**, both of the bent portions project from the case **10** in the direction *x*, as viewed in the direction *z*.

The lead **34** corresponds to the fourth lead of the present invention and includes a bonding portion **34a**, a wire bonding portion **34b**, and a mounting terminal surface **34d**. As shown in FIG. **1**, the bonding portion **34a** and the wire bonding portion **34b** are arranged in the region surrounded by the reflector **11** at a position shifted further to the left in the figure than the lead **31** in the direction *x*.

To the bonding portion **34a** is bonded the Zener diode **41** via a conductive material. The wire bonding portion **34b** is on the right side of the bonding portion **34a** in the direction *x* and arranged side by side with the wire bonding portion **31b** of the lead **31** in the direction *y*. To the wire bonding portion **34b** is bonded an end of the wire **34**. The other end of the wire **54** is bonded to the LED chip **21**.

Of the lead **34**, the portion projecting from the case **10** downward in the direction *y* in FIG. **1** is bent to extend in the direction *z*, as shown in FIGS. **1**, **2**, **4** and **5**. Of this portion, the surface that faces downward in the direction *y* in FIG. **1** is the mounting terminal surface **34d**. The bent portion extends to overlap the recess **12** of the case **10** in the direction *z*.

The lead **35** corresponds to the fifth lead defined in the present invention and includes a bonding portion **35a**, a wire bonding portion **35b**, and a mounting terminal surface **35d**. As shown in FIG. **1**, the shape of the lead **35** is symmetrical with the lead **34** with respect to an axis extending in the direction

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y. The bonding portion **35a** and the wire bonding portion **35b** are arranged in the region surrounded by the reflector **11** at a position shifted further to the right in the figure than the lead **32** in the direction *x*.

To the bonding portion **35a** is bonded, the Zener diode **42** via a conductive material. The wire bonding portion **35b** is on the left side of the bonding portion **35a** in the direction *x* and arranged side by side with the wire bonding portion **32b** of the lead **32** in the direction *y*. To the wire bonding portion **35b** is bonded an end of the wire **55**. The other end of the wire **55** is bonded to the LED chip **22**.

Of the lead **35**, the portion projecting from the case **10** downward in the direction *y* in FIG. **1** is bent to extend in the direction *z*, as shown in FIGS. **1**, **2**, **4** and **5**. Of this portion, the surface that faces downward in the direction *y* in FIG. **2** is the mounting terminal surface **35d**. The bent portion extends to overlap the recess **12** of the case **10** in the direction *z*.

The lead **36** corresponds to the sixth lead defined in the present invention, and includes a wire bonding portion **36b** and amounting terminal surface **36d**. As shown in FIG. **1**, the bonding portion **36b** is arranged at the center in the direction *x* in the region surrounded by the reflector **11**. Also, the bonding portion **36b** is at a lower position relative to the bonding portion **33a** in the direction *y* in FIG. **1**. To the wire bonding portion **36a** is bonded an end of wire **53**. The other end of the wire **53** is bonded to the LED chip **33**.

The light-transmitting resin **60** fills the region surrounded by the reflector **11** and covers the LED chips **21**, **22**, **23** and the Zener diodes **41**, **42**. The light-transmitting resin **60** is made of e.g. transparent silicone resin.

Advantages of the LED module **100** are described below.

In this embodiment, the LSD chips **21**, **22** and **23** are arranged at positions corresponding to three vortexes of a triangle. This arrangement allows the three LSD chips **21**, **22**, **23** to be positioned relatively close to each other, as compared with e.g. the case where the LED chips are arranged in a line. Thus, lights emitted from the respective LED chips can properly mix with each other, so that light emission of a bright white color is obtained. Arranging the LED chip **23** that emits red light at the center in the direction *x* promotes mixing of red light, blue light and green light. Moreover, the LED module **100** can be made compact by arranging the LED chips **21**, **22**, **23** close to each other.

The provision of the mounting terminal surfaces **31d**, **32d**, **33d**, **34d**, **35d**, **36d** allows individual operation of the LED chips **21**, **22**, **23**.

The wire **53** extends from the LED chip **23** in the direction *y* beyond a line connecting the LED chips **21** and **22** to each other. Thus provided wire **53** hardly hinders the reduction of the distance between the LED chips **21** and **22**. This is advantageous for promoting the above-described mixing of light and size reduction of the LED module **100**.

The wires **51**, **52**, **54** and **55** are configured to extend away from the LED chip **23** in the direction *x*. Thus, though the LED chips **21** and **22** are of a two-wire type, no wires **51**, **52**, **54**, **55** exist in the region surrounded by the LED chips **21**, **22** and **23**. This allows reduction of the distance among the LED chips **21**, **22**, **23**. Employing a single-wire type LED chip as the LED chip **23** reduces the number of the wires existing in the region surrounded by the LED chip **21**, **22** and **23**.

The bonding portion **33a** is arranged on the opposite side from a circuit board upon which the module is mounted. The mounting terminal surfaces **33d** are spaced apart from the bonding portion in the direction *y*. In spite of this, the detour portion **33e** connects the bonding portion **33a** and each of the mounting terminal surfaces **33d** properly, and substantially with no hindrance to possible arrangements of the leads **31**,

32, 34, 35, 36. Advantageously, the LED module **100** can be made relatively compact in spite of the provision of a large number of mounting terminal surfaces **31d, 32d, 33d, 34d, 35d** and **36d**.

As shown in FIG. **6**, the groove **31c** functions to stop the flow of the bonding material for die-bonding the LED chip **21**. Thus, the bonding material is prevented from flowing from the bonding portion **31a** to the wire bonding portion **31b**, which allows the bonding portion **31a** and the wire bonding portion **31b** to be arranged closer to each other. This is desirable for the size reduction of the LED module **100**. The groove **32c** similarly contributes to the size reduction of the LED module **100**.

As shown in FIG. **3**, owing to the provision of the recess **12**, the respective reverse surfaces of the mounting terminal surfaces **31d, 32d, 34d, 35d, 23d** of the leads **31, 32, 34, 35, 36** are exposed. For instance, after the LED module **100** is mounted on a circuit board or the like, some of the LED chips **21, 22, 23** may be found to be inoperable due to poor soldering. Even in such a case, since the above-described reverse surfaces are exposed, it is possible to conduct an operation for coping with the fault, such as applying a soldering iron to the poor joint portion. The projection of the reverse surfaces of the mounting terminal surfaces **33d** of the lead **33** from the case **10** to each side in the direction **x** also allows a similar operation to be conducted.

The LED module according to the present invention is not limited to the foregoing embodiment. The specific structure of each part of the LED module according to the present invention can be varied in design in many ways.

Although the provision of the LED chip **21** that emits blue light, the LED chip **22** that emits green light and the LED chip **23** that emits red light is desirable in order for the LED module **100** to emit white light, the present invention is not limited to this, and LED chips that emit light of different wavelengths can be employed.

The invention claimed is:

1. An LED module comprising:

a first and a second LED chips spaced apart from each other;

a third LED chip arranged at a position that is offset from a straight line connecting the first and the second LED chips, said position being between the first LED chip and the second LED chip in a spacing direction in which the first and the second LED chips are spaced apart from each other;

a first lead including a first die bonding portion on which the first LED chip is mounted, a first wire bonding portion spaced apart from the first die bonding portion in the spacing direction, and a first mounting terminal surface for surface-mounting;

a first wire connecting the first LED chip and the first wire bonding portion to each other;

a second lead including a second die bonding portion on which the second LED chip is mounted and a second mounting terminal surface for surface-mounting; and

a third lead including a third die bonding portion on which the third LED chip is mounted and a third mounting terminal surface for surface-mounting;

wherein the first through the third mounting terminal surfaces are flush with each other,

light from each of the first through the third LED chips is emitted in a direction in which the first through the third mounting terminal surfaces extend,

the first lead is formed with a groove positioned between the first die bonding portion and the first wire bonding portion, the groove extending in a direction crossing the spacing direction, and

the first wire bridges over the groove.

2. The LED module according to claim **1**, wherein one of the first and the second LED chips emits blue light, the other one of the first and the second LED chips emits green light, and the third LED chip emits red light.

3. The LED module according to claim **2**, further comprising a second wire including an end bonded to the third LED chip, the second wire extending across the straight line connecting the first and the second LED chips.

4. The LED module according to claim **2**, wherein the first wire extends from the first LED chip in a direction away from the third LED chip in the spacing direction.

5. The LED module according to claim **1**, wherein the third lead comprises a detour portion extending in the spacing direction and passing at least one of the first and the second LED chips, the detour portion being provided between the third die bonding portion and the third mounting terminal surface.

6. The LED module according to claim **1**, further comprising a Zener diode arranged opposite to the third LED chip with respect to the first LED chip in the spacing direction, the Zener diode being connected in series to the first LED chip.

7. The LED module according to claim **1**, further comprising:

a second wire including an end bonded to the first LED chip;

a fourth lead including a second wire bonding portion to which another end of the second wire is bonded and also including a fourth mounting terminal surface for surface mounting;

a third wire including an end bonded to the second LED chip;

a fifth lead including a third wire bonding portion to which another end of the third wire is bonded and also including a fifth mounting terminal surface for surface mounting;

a fourth wire including an end bonded to the third LED chip;

and

a sixth lead including a fourth wire bonding portion to which another end of the fourth wire is bonded and also including a sixth mounting terminal surface for surface mounting;

wherein the first through the sixth mounting terminal surfaces are flush with each other.

8. The LED module according to claim **7**, further comprising a case, wherein the case is provided with a recess, and the first through the sixth leads include surfaces opposite to the first through the sixth mounting terminal surfaces, respectively, wherein the recess of the case exposes at least a part of each of the opposite surfaces of the first through the sixth leads, as viewed from a side opposite to a direction in which the first through the sixth mounting terminal surfaces face.

9. The LED module according to claim **1**, further comprising a case, wherein the case is provided with a reflector surrounding the first through the third LED chips.

10. The LED module according to claim **9**, wherein the reflector surrounds a region filled with light-transmitting resin covering the first through the third LED chips.